Product Update

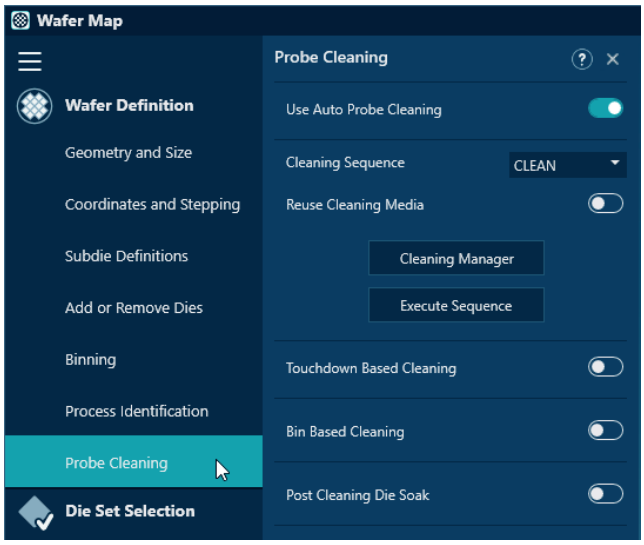
Velox™ 3.4.3 Highlights

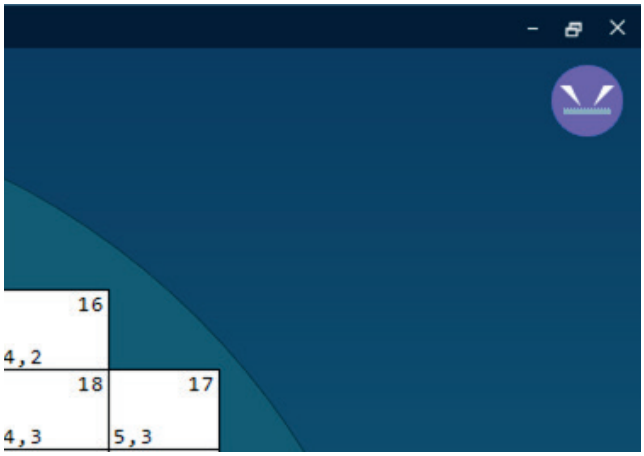
Probe Station Control Software

The most powerful engineering software in the market

Velox 3.4.3 comes with a modernized toolbar and new Wafer Map features. These include touchdown-based and bin-based Auto Probe Cleaning, Cluster Support and optimized Subdie binning. Autonomous RF has been optimized for robustness with Intelligent Error Management.

Velox software upgrades are free for existing customers.*





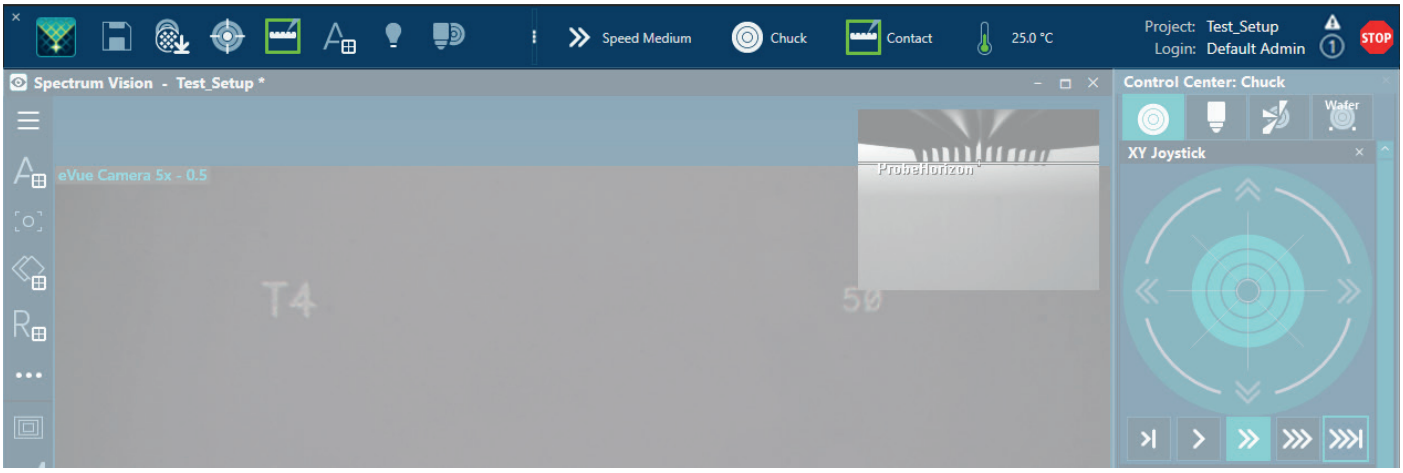
Auto Probe Cleaning

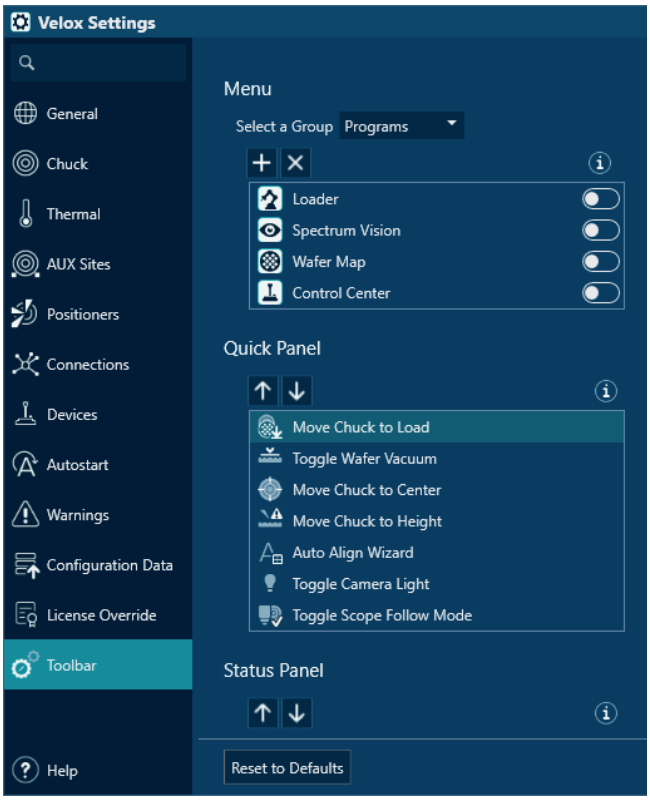
Auto Probe Cleaning is a new feature in Velox Wafer Map. It triggers an automated probe cleaning operation after a specified number of probe touchdowns and/or consecutive binning fails. An indicator is displayed in the upper right corner of Wafer Map when Use Auto Probe Cleaning is enabled.

Benefit:

More robust and precise measurements with less user intervention.

Modernized Toolbar



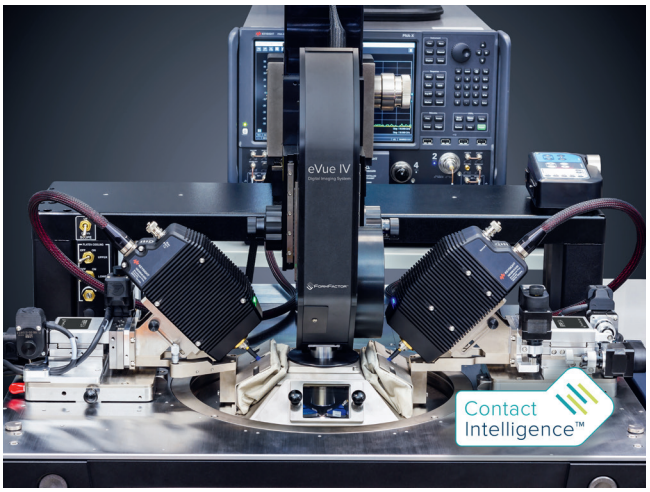


The Velox Toolbar has been completely rewritten to better support high-resolution displays. Status symbols, information labels and buttons have been optimized.

The Toolbar setup is now available in Velox settings. Existing buttons and status information can be enabled / disabled. New custom buttons containing Velox commands can be easily created and added to the Toolbar.

Benefit:

Easier to monitor system behavior, status and warnings. Full customization to user needs.

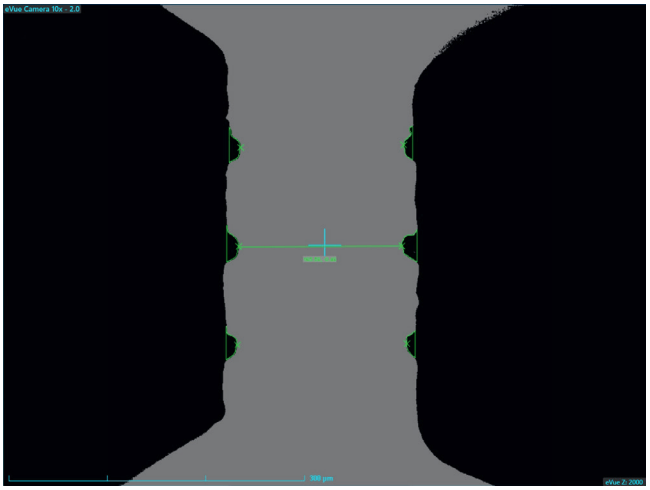


Auto RF Intelligent Error Management

Intelligent Error Management has been integrated into the Autonomous RF Measurement Assistant. This contains recovery actions that make probe-to-pad alignment and automatic calibrations more precise, robust and reliable.

Benefit:

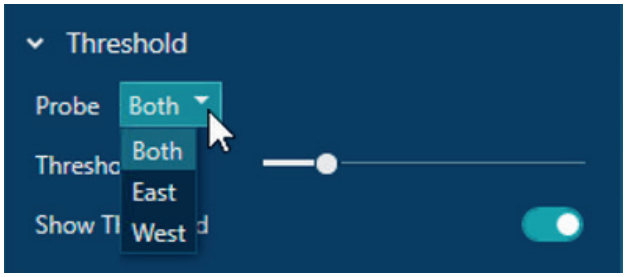
More precise, robust and reliable automation of RF calibration and measurement.

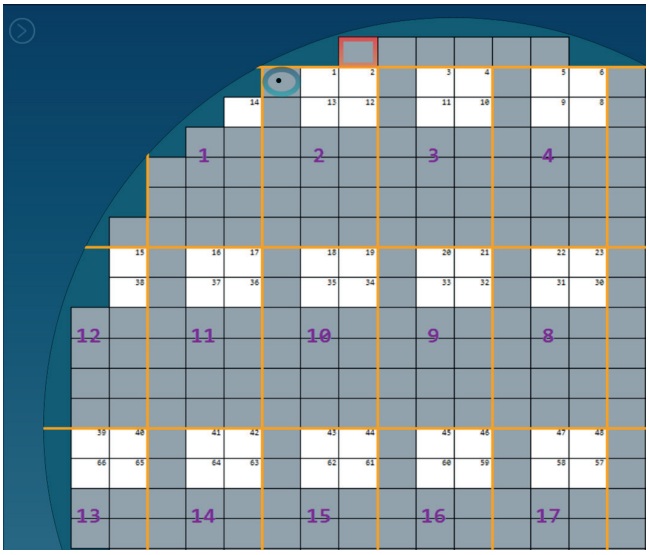


Auto RF Training Wizard Update

In the Auto RF training Wizard, it is now possible to select dfferent thresholds for the East and West probes.

Benefit:
Better blob analysis results when probes look slightly different from each other.



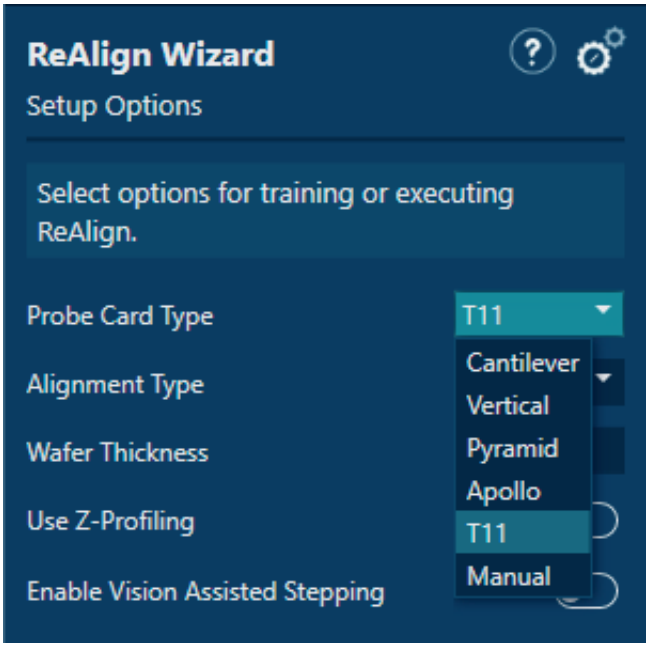


Cluster Support

Clusters are now supported in Wafer Map. They represent an additional layer to die layer and subdie layer. Clusters can be used to group dies on multi-project wafers, for example 3x6 dies. They can be useful in projects with multi-contact probe cards.

In the Wafer Map, cluster borders are represented as orange lines.

Benefit:
Higher efficiency when testing multi-project wafers and with multi-contact probe cards.

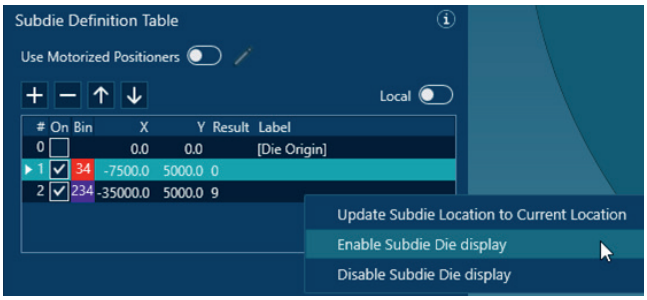


T11 Probe Card Support within ReAlign™

A new algorithm for T11 Probe Cards has been added to ReAlign™. With the new algorithm, it is now possible to perform automated probe-to-pad alignment at different temperatures with T11 Probe Cards.

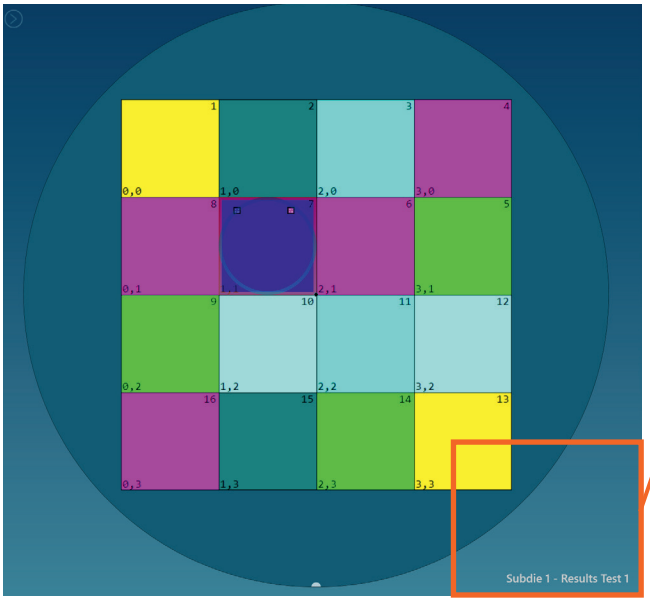
Benefits:
Automated probe-to-pad alignment over multiple temperatures with T11 probe cards.

Show Bin Colors of a Subdie on the Wafer Map Die Display

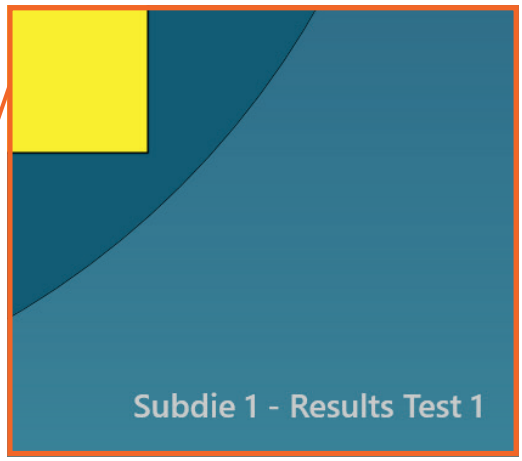


Bin colors of subdies can now be shown on the Wafer Map die display.

Different subdies and their corresponding binning results for various different measurements can be selected and displayed individually.



Benefits:
Faster subdie binning analysis at a glance.



** Requires a Service visit. Depending on the current system state, a Velox upgrade might require an upgrade of the probe station PC. Please contact your local sales person for more information.*